

## **AMENDMENTS TO THE SPECIFICATION**

**Please replace the paragraph beginning at page 1, line 4, with the following rewritten paragraph:**

This application is a ~~divisional~~ continuation-in-part of U.S. Patent Application Serial No. 09/758,822, filed January 11, 2001 by William Grant, now U.S. Patent No. 6,703,703 entitled Low Cost Power Semiconductor Module Without Substrate which is application relates and claims priority to a United States provisional application, Ser. No. 60/175,802, entitled Low Cost Power Semiconductor Module Without Substrate, filed in the United States Patent and Trademark Office on January 12, 2000.

**Please replace the paragraph beginning at page 2, line 15, with the following rewritten paragraph:**

Figure 2 is a cross-section of the lead frame of Figure 1 taken across section line 2-2 in Figure 1 as incorporated in a module according to the present invention.

**Please replace the paragraph beginning at page 4, line 25, with the following rewritten paragraph:**

Thus, after the die S1 to S6 are bonded to their various lead frame pads, the lead frame is insert molded in an insulation housing 50 and the lead frame bridging sections (exterior of the dotted line in Figure 1) are removed to separate the ~~pads~~ leads from one another and the lead frames are thus singulated.

**Please replace the paragraph beginning at page 5, line 3, with the following rewritten paragraph:**

Alternatively, the lead frame may be first insert molded in the insulation housing 50, and the lead frame bridging sections removed, thereby singulating the ~~pads~~ leads from one another.

Then, the die S1 to S6 may be bonded to their various lead frame pads, and wire bonded to one another.